

The invention is a method of forming an array of caps for attachment to a wafer which includes a plurality of microfabricated devices. The method includes sandwiching a sheet (134) of thermoplastic material between upper and lower molds (102, 104), heating the sheet to a plastic state and molding the sheet into caps. The molds (102, 104) are preferably formed of silicon and infrared radiation is preferably used to heat the sheet (134).